

JMV4852P

Product Preview

30V 32A P-Channel MOSFET

Features

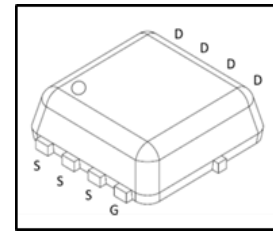
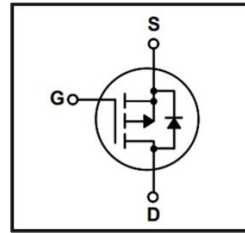
- Advanced trench technology
- Ultra-low on-resistance
- RoHS compliant
- 100% avalanche tested



Product Summary	
V_{DS}	-30V
$R_{DS(ON)}$	7.6 m Ω (Typ.)
	9.8 m Ω (Max.)
I_D	-32A

Applications

- Motor controllers
- DC-to-DC convertors
- Battery-driven electronic products, electrical equipment and machines


Ordering Information

Part Number	Marking	Package	Packaging
JMV4852P	V4852P	DFN3.3x3.3	Tape & Reel

Absolute Maximum Ratings

Parameter	Symbol	Limit	Unit
Drain-to-Source Voltage	V_{DS}	-30	V
Gate-to-Source Voltage	V_{GS}	± 20	
Continuous Drain Current, Package Limited ($T_C = 25^\circ\text{C}$) ⁽¹⁾	I_D	-32	A
Continuous Drain Current, Silicon Limited ($T_C = 25^\circ\text{C}$) ⁽¹⁾	I_D	-58	
Continuous Drain Current, Silicon Limited ($T_C = 100^\circ\text{C}$) ⁽¹⁾	I_D	-36	
Continuous Drain Current, Silicon Limited t ($T_A = 25^\circ\text{C}$) ^{(2), (5)}	I_D	-11	
Continuous Drain Current, Silicon Limited ($T_A = 100^\circ\text{C}$) ^{(2), (5)}	I_D	-7	
Pulsed Drain Current ⁽³⁾	I_{DM}	-128	
Power Dissipation ($T_C = 25^\circ\text{C}$)	P_D	52.1	W
Linear Derating Factor	-	0.42	W/ $^\circ\text{C}$
Single Pulse Avalanche Energy ⁽⁴⁾	E_{AS}	75	mJ
Avalanche Current	I_{AS}	28	A
Junction Temperature	T_J	-55 to 150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55 to 150	

Thermal Characteristics

Parameter	Symbol	Max	Unit
Junction-to-Ambient Thermal Resistance ⁽⁵⁾	$R_{\theta JA}$	62	$^\circ\text{C}/\text{W}$
Junction-to-Case Thermal Resistance	$R_{\theta JC}$	2.4	

Static Electrical Characteristics⁽⁶⁾

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-to-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0\text{V}, I_D = -250\mu\text{A}$	-30	-	-	V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-1.0	-	-2.0	
Drain-to-Source Leakage Current	I_{DSS}	$V_{DS} = -30\text{V}, V_{GS} = 0\text{V}$	-	-	-1	μA
Gate-to-Source Leakage Current	I_{GSS}	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$	-	-	± 100	nA
Drain-to-Source On-Resistance	$R_{DS(ON)}$	$V_{GS} = -10\text{V}, I_D = -10\text{A}$	-	7.6	9.8	$\text{m}\Omega$
		$V_{GS} = -4.5\text{V}, I_D = -10\text{A}$	-	9.5	12.3	$\text{m}\Omega$

Dynamic Electrical Characteristics ⁽⁶⁾

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Forward Transconductance	g_{fs}	$V_{DS} = -5V, I_D = -20A$	-	68	-	S
Total Gate Charge	Q_g	$V_{GS} = -10V,$	-	64	-	nC
Gate-to-Source Charge	Q_{gs}	$V_{DS} = -15V,$	-	9	-	
Gate-to-Drain Charge	Q_{gd}	$I_D = -20A$	-	10	-	
Turn-On Delay Time	$t_{d(on)}$	$V_{GS} = -10V,$	-	6	-	ns
Rise Time	t_r	$V_{DS} = -15V,$	-	22	-	
Turn-Off Delay Time	$t_{d(off)}$	$I_D = -20A,$	-	84	-	
Fall Time	t_f	$R_G = 3.0\Omega$	-	17	-	
Input Capacitance	C_{iss}	$V_{GS} = 0V,$	-	2950	-	pF
Output Capacitance	C_{oss}	$f = 1MHz,$	-	275	-	
Reverse Transfer Capacitance	C_{rss}	$V_{DS} = -15V$	-	130	-	

Diode Characteristics ⁽⁶⁾

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Forward Voltage	V_{SD}	$V_{GS} = 0V, I_S = -10A$	-	-0.9	-	V
Reverse Recovery Time	t_{rr}	$V_{GS} = 0V, I_S = -10A,$	-	40	-	ns
Reverse Recovery Charge	Q_{rr}	$di_S/dt = -100A/\mu s$	-	43	-	nC

(1) Rated according to $R_{\theta JC}$.

(2) Rated according to $R_{\theta JA}$.

(3) Limited by maximum T_J .

(4) $T_A = 25^\circ C, L = 0.1mH, I_{AS} = 28A$.

(5) Surface-mounted on 1 inch² FR4 board, 2 oz Cu.

(6) $T_J = 25^\circ C$ unless otherwise specified.

Typical Electrical Characteristics

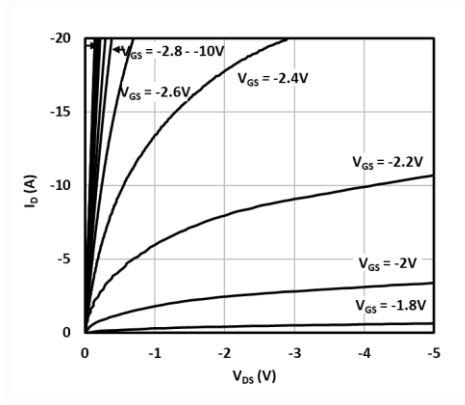


Fig. 1 Output characteristics

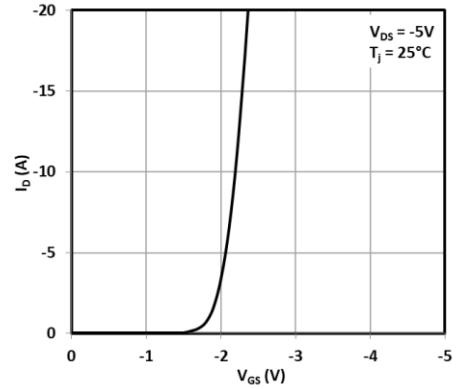


Fig. 2 Transfer characteristics

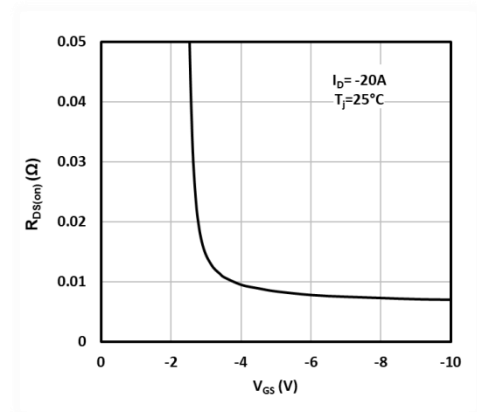


Fig.3 On-resistance vs. gate voltage

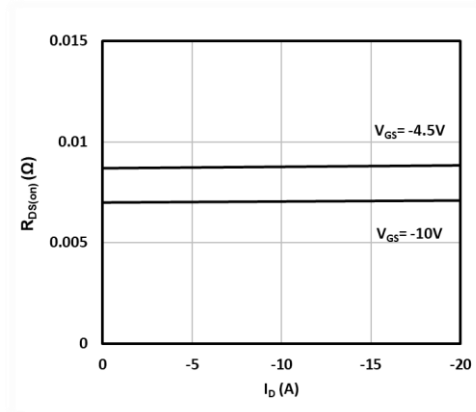


Fig.4 On-resistance vs. drain current

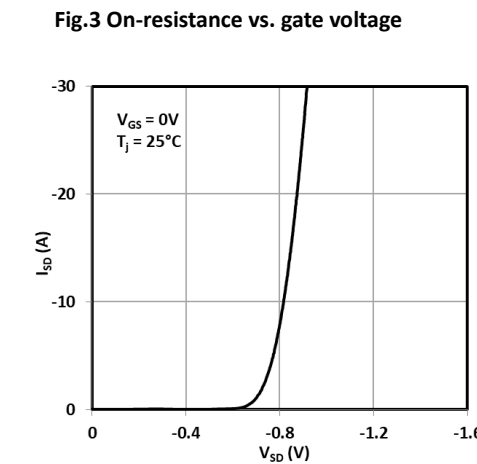


Fig.5 Source-to-drain diode forward characteristics

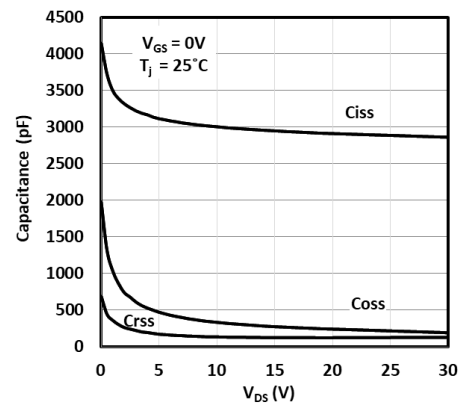


Fig.6 Capacitance vs. drain-to-source voltage

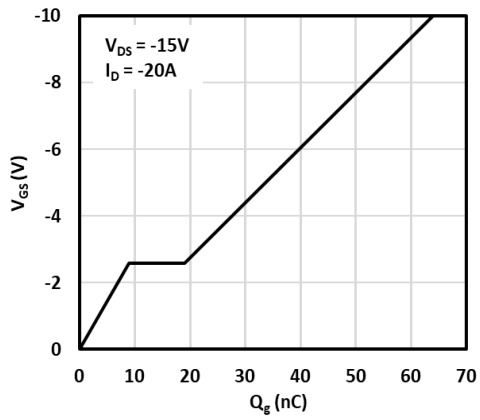


Fig.7 Gate-to-source voltage vs. gate charge

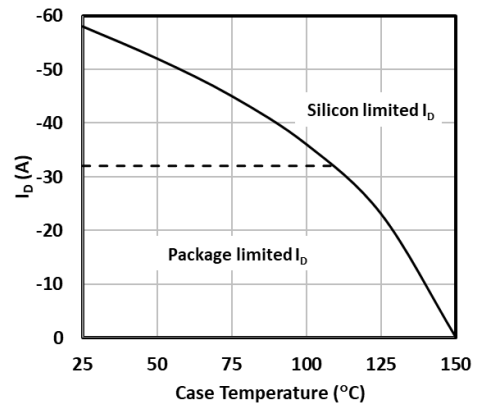


Fig.8 Maximum drain current vs. case temperature

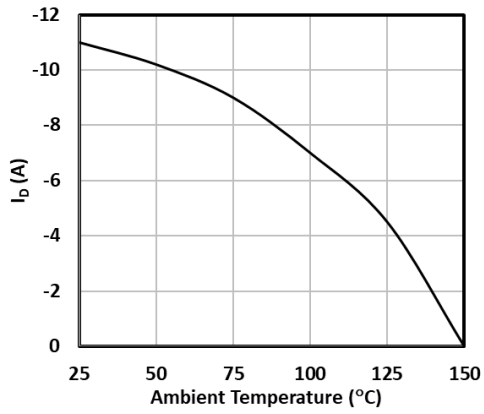
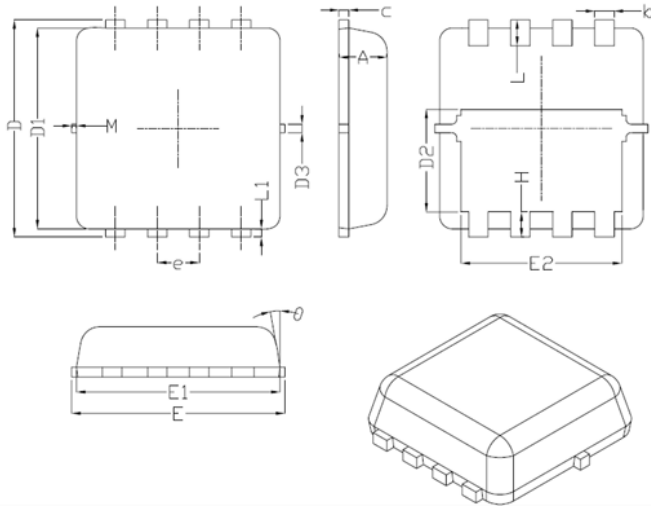


Fig. 9 Maximum drain current vs. ambient temperature

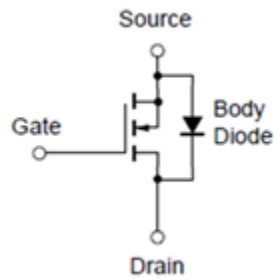
Package Drawing



DIM.	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.70	0.80	0.90
b	0.25	0.32	0.39
c	0.10	0.15	0.25
D	3.00	3.30	3.60
D1	3.00	3.10	3.50
D2	1.48	2.00	2.20
D3	--	0.20	--
E	3.00	3.30	3.60
E1	3.00	3.10	3.25
E2	2.29	2.49	2.69
e	0.65 BSC		
H	0.15	0.25	0.50
L	0.15	0.40	0.60
L1	0.05	0.15	0.25
α	8°	10°	12°
M	--	0.10	--

DFN 3.3x3.3

Equivalent Circuit



Revision history of JMV4852P specification

Version	Change Items	Effective Date
1.00	Initial Release	28-Feb-20

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